

APPENDIX

Changes to Claims:

The following is a marked-up version of the amended claim:

21. (Amended) A semiconductor device comprising:

a semiconductor chip having electrodes; a substrate on which an interconnect pattern is formed; a protective layer provided on said substrate excluding a region of said interconnect pattern of electrical connection with said electrodes of said semiconductor chip; and a conductive adhesive;

wherein said adhesive is provided on said substrate from a region of mounting of said semiconductor chip to said protective layer, said adhesive, said protective layer and said interconnect pattern overlapping with one another outside of said region of mounting of said semiconductor chip; and

wherein said electrodes of said semiconductor chip are electrically connected with said interconnect pattern.